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(54) Title (EN): FLEXIBLE SUBSTRATE

(54) Title (FR): SUBSTRAT SOUPLE

(54) Title (JA): フレキシブル基板

(57) Abstract:

(EN): A flexible substrate according to one embodiment of the present invention is provided with: a flexible insulating base material; and a plurality of wiring lines that are provided on one surface of the insulating base material. This flexible substrate is configured such that: the insulating base material has a thinned first region and a second region that has a larger film thickness than the first region; the first region has a first lower surface; the second region has a second lower surface; the first lower surface and the second lower surface are formed in a surface of the insulating base material, said surface being on the reverse side of the surface on which the wiring lines are provided; and the first lower surface has an inclined part that is inclined toward the second lower surface.

(FR): Un substrat souple selon un mode de réalisation de la présente invention est pourvu : d'un matériau de base isolant souple ; et d'une pluralité de lignes de câblage qui sont disposées sur le matériau de base isolant. Ce substrat souple est configuré de telle sorte que : le matériau de base isolant a une première région amincie et une seconde région qui a une épaisseur de film plus grande que la première région ; la première région a une première surface inférieure ; la seconde région a une seconde surface inférieure ; la première surface inférieure et la seconde surface inférieure sont formées dans une surface du matériau de base isolant, ladite surface étant sur le côté inverse de la surface sur laquelle les lignes de câblage sont disposées ; et la première surface inférieure a une partie inclinée qui est inclinée vers la seconde surface inférieure.

(JA): 本実施形態に係るフレキシブル基板は、可撓性の絶縁基材と、前記絶縁基材の一方の面側に設けられた複数の配線と、を備え、前記絶縁基材は、薄膜化された第1領域と、前記第1領域より膜厚が大きい第2領域と、を有し、前記第1領域は第1下面を有し、前記第2領域は第2下面を有し、前記第1下面と前記第2下面は、前記絶縁基材の配線が設けられた面側と反対側の面側に形成され、前記第1下面は、前記第2下面にかけて傾斜した傾斜部を有する。

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